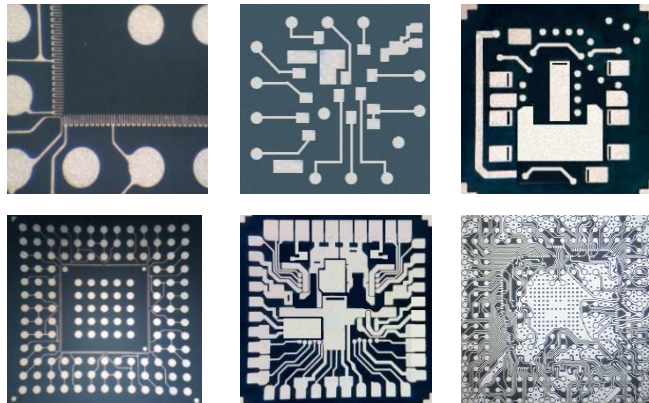


NEWS RELEASE

**ASMPT and SPIL Announce Joint Investment Venture in Molded Interconnect Substrates (“MIS”)**



MIS provides fine routable traces for wire-bonding and flip chip packages

**Hong Kong and Singapore, 23 October 2015** - ASM Pacific Technology Limited (“ASMPT”) (HKG: 0522), and Siliconware Precision Industries Co., Ltd. (“SPIL”) (TSE: 2325.TT, NASDAQ:SPIL) announced today that both companies will enter into an agreement to establish a joint investment entity to develop and manufacture molded interconnect substrates (“MIS”) to meet the industry’s demand for advanced semiconductor chips with greater functionality.

The entity, ASM Advanced Packaging Materials Pte. Ltd. (“AAPM”), will be formed through acquiring, amongst other things, the equipment and assets, the intellectual property rights and know-how of Interconnect Tech Pte Ltd (“iCT”), a Singapore-based company offering one-stop MIS solutions to the semiconductor industry. Through its subsidiary, ASMPT will hold a majority of the shares of AAPM, and will also be responsible for managing the business and operations of AAPM.

In recent years, market adoption of advanced packaging technologies has grown significantly, driven by consumer demand for electronic products including mobile and wearable devices to have thinner and smaller form factors as well as higher performance with excellent electrical and thermal properties. MIS substrates are multiple-layer redistribution layer (RDL) carriers for advanced packages using pre-mold technology. They have fine routable traces and copper pads which support wire-bonding, flip chip bonding, and multi-chip packages in meeting the critical requirements for advanced packaging applications like System-in-Packages (SiP), cost-effective alternative to wafer level fan out (WLFO), and devices for Internet of Things (IoT), radio frequency (RF) application and power management. Early adopters of MIS include, but not limited to, Infineon Technologies and other major partners of leading smartphone manufacturers.

Mr Stanley Tsui, Executive Vice President and CEO of Materials Business segment of ASMPT said: “In the past few years, ASMPT has been aggressively investing in advanced packaging equipment solutions. With this investment, ASMPT extends our offerings to advanced packaging materials which will enable us to provide customers a broader range of packaging solutions. We are excited to set up this business venture with SPIL, a leading provider of comprehensive semiconductor assembly and test services. Leveraging our capabilities and know-how in advanced packaging, we will be able to offer customers cost-optimised value-added packaging solutions.”

Mr Patrick Lin, Vice President of Procurement of SPIL said: “We believe that ASMPT is an ideal partner for SPIL for the development and investment of MIS. SPIL has a long-time business relationship with ASMPT and this partnership will bring benefits and value of MIS to customers at a much faster speed-to-market.”

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#### **About ASM Pacific Technology Limited**

ASM Pacific Technology Limited (“ASMPT”) (HKG: 0522), as a global technology and market leader, develops and provides leading edge solutions and materials for semiconductor assembly and packaging industries, as well as surface mount technology applications in a wide range of end-user markets including electronics, mobile communications, automotive, industrial, LED and solar energy. ASMPT consistently invests in R&D to provide customers with innovative and cost-efficient solutions and systems that help them to achieve higher productivity, greater reliability and enhanced quality.

Listed on the Hong Kong Stock Exchange in 1989, ASMPT is currently one of the constituent stocks on the Hang Seng HK Mid-cap Index under the Hang Seng Composite Index, the Hang Seng Information Technology Industry Index, the Hang Seng Hong Kong 35 Index and the Hang Seng Global Composite Index. To learn more about ASMPT, please visit [www.asmpacific.com](http://www.asmpacific.com).

#### **About Siliconware Precision Industries Co., Ltd.**

Siliconware Precision Industries Ltd. (“SPIL”) (NASDAQ:SPIL, Taiwan Stock Exchange:2325) is a leading provider of comprehensive semiconductor assembly and test services. SPIL is dedicated to meeting all of its customers' integrated circuit packaging and testing requirements, with turnkey solutions that range from design consultations, modelling and simulations, wafer bumping, wafer probe and sort, package assembly, final test, burn-in, to shipment. Products include advanced leadframe, substrate packages, wafer bumping and FCBGA, which are widely used in personal computers, communications, Internet appliances, cellular phones, digital cameras, cable modems, personal digital assistants and LCD monitors. SPIL supplies services and support to fabless design houses, integrated device manufacturers and wafer foundries globally. For further information, visit SPIL's web site at [www.spil.com.tw](http://www.spil.com.tw).

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